## ML1001 Series Static LCD COG Driver

## * Application

- Instrument LCD Module
- Telephone LCD Module
- Automotive LCD Module
- Handheld Device LCD Module


## * Features

- AGoldBumpChip without extemal component.
- Logic \& LCD power supply: 2.0 V to 6.0 V
- Typical Current consumption: 25 uA at $\mathrm{V}_{\text {IN }}=3 \mathrm{~V}$ \& no load condition.
- Number of segments: 40
- Cascade the ML1001 to form a single piece of 80 or 120 segments LCD driver.
- Simple 3pin microcontroller interface throughDIN, DCLK \& LOAD.
- Blink of the display data.
- Offer best contrast and widest viewing angle of TNLCD technology.
- No temperature compensation needed for $\mathrm{Topr}=-40^{\circ} \mathrm{C}$ to $80^{\circ} \mathrm{C}$.


## * General Description

ML1001 static LCD COG (chip on glass) driver is 40 segments LCD driver with gold bump. It can be cascaded to form a single piece of 80 or 120 segments LCD drivers. It targets at custom TN LCD COG Module product which requires the best quality of TN LCD technology. With the use of ML1001 series driver, it offers the best contrast, the widest viewing angle, the widest range of operating voltage and the widest range of operating temperature when compared to the multiplex method.

Our ML1001 includes an internal 32 kHz oscillator, a 40-bit shift register, a 40-bit data register, a 16 -bit segment driver, a 24 -bit segment driver, two common drivers, a blink control circuit, a power-up reset circuit and a frequency divider which offer the necessary clock signals for Blink control, segment \& common driver circuit.

Through the DIN pin, the display data is serially shifted into the 40-bit shift register at the rising edge of DCLK signal. The display data, which is going to be displayed on the attached LCD, is then stored in the 40-bit data register at the rising edge of the LOAD signal.

Other features like blinking of the display data by the BEN and BCLK, disable the internal oscillator by the OEN, input an external clock signal to the FIN, and enable or disable the segment and common driver by the SEN1, SEN2, CEN1A and CEN1B, are included.

## * Ordering Information

| Part Number | Description | Package Form |
| :--- | :--- | :--- |
| ML1001-1U | a 40 segment static LCD driver | Gold Bump Die |
| ML1001-2U | a 80 segment static LCD driver | Gold Bump Die |
| ML1001-3U | a 120 segment static LCD driver | Gold Bump Die |

## * Block Diagram



## * Absolute Maximum Ratings

| Parameter | Symbol | Condition | MIN | MAX | Unit |
| :--- | :--- | :--- | :--- | :--- | :--- |
| Supply voltage | $\mathrm{V}_{\mathrm{DD}}$ |  | -0.5 | +7.0 | V |
| Supply Current | $\mathrm{I}_{\mathrm{DD}}$ | $\mathrm{V}_{\mathrm{DD}}=3 \mathrm{~V}$, no Load | -50 | +50 | mA |
| Input Voltage | $\mathrm{V}_{\mathrm{IN}}$ |  | GND-0.3 | $\mathrm{V}_{\mathrm{DD}}+0.3$ | V |
| Output Voltage | $\mathrm{V}_{\text {OUT }}$ |  | GND-0.3 | $\mathrm{V}_{\mathrm{DD}}+0.3$ | V |
| DC input Current | $\mathrm{I}_{\mathrm{IN}}$ |  | -10 | +10 | mA |
| DC output Current | $\mathrm{I}_{\text {OuT }}$ |  | -10 | +10 | mA |
| Storage temperature | $\mathrm{T}_{\text {stg }}$ |  | -65 | +150 | ${ }^{\circ} \mathrm{C}$ |
| Total power dissipation | $\mathrm{P}_{\text {tot }}$ |  | - | 400 | mW |

## * DC Characteristic

$\mathrm{V}_{\mathrm{DD}}=3.0 \mathrm{~V} ; \mathrm{T}_{\mathrm{amb}}=25^{\circ} \mathrm{C}$; unless otherwise specified

| Parameter | Symbol | Condition | MIN | TYP | MAX | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Supplies |  |  |  |  |  |  |
| Supply voltage | $\mathrm{V}_{\text {DD }}$ |  | 2.0 | - | 6.0 | V |
| Supply Current | $\mathrm{I}_{\mathrm{DD}}$ | Disable Oscillator | - | 0.1 | 0.5 | uA |
| Supply Current | $\mathrm{I}_{\mathrm{DD}}$ | Enable Oscillator | - | 25 | 60 | uA |
| Logic |  |  |  |  |  |  |
| LOW-level input voltage | $\mathrm{V}_{\text {IL }}$ |  | GND | - | $0.3 *{ }^{\text {DD }}$ | V |
| HIGH-level input voltage | $\mathrm{V}_{\mathrm{IH}}$ |  | $0.7 * \mathrm{~V}_{\mathrm{DD}}$ | - | $\mathrm{V}_{\text {DD }}$ | V |
| LOW-level output current | $\mathrm{I}_{\text {OL }}$ | $\mathrm{V}_{\text {OL }}=1.0 \mathrm{~V}$ | 1 | - | - | mA |
| HIGH-level output current | IOH | $\mathrm{V}_{\mathrm{OH}}=2.0 \mathrm{~V}$ | -1 | - | - | mA |
| LCD outputs |  |  |  |  |  |  |
| Output resistance at pads S1 to S40 | $\mathrm{R}_{\text {SEG }}$ |  | - | 85 | 150 | ohm |
| Output resistance at pads COM1A and COM1B | $\mathrm{R}_{\text {COM }}$ |  | - | 45 | 100 | ohm |

## * AC Characteristic

$\mathrm{V}_{\mathrm{DD}}=3.0 \mathrm{~V} ; \mathrm{T}_{\mathrm{amb}}=25^{\circ} \mathrm{C}$; unless otherwise specified

| Parameter | Symbol | Conditions | MIN | TYP | MAX | Unit |
| :--- | :--- | :--- | :--- | :--- | :--- | :--- |
| Oscillator frequency at <br> pad OOUT | $\mathrm{f}_{\text {oout }}$ |  | 21 | 32 | 48 | kHz |
| FIN, LOAD, DIN, DCLK <br> High time | $\mathrm{t}_{\mathrm{H}}$ |  | 0.4 | - | - | us |
| FIN, LOAD, DIN, DCLK <br> Low time | $\mathrm{t}_{\mathrm{L}}$ |  | 0.4 | - | - | us |
| FIN, LOAD, DIN, DCLK <br> Rise time | $\mathrm{t}_{\mathrm{r}}$ |  | - | - | 10 | us |
| FIN, LOAD, DIN, DCLK <br> Fall time | $\mathrm{t}_{\mathrm{f}}$ |  | - | - | 10 | us |
| DCLK Frequency | $\mathrm{F}_{\text {DCLK }}$ |  | 1 | - | 100 | kHz |
| Baudrate |  |  |  |  |  |  |

## * Timing Diagram



## Functional Description

The ML1001 is a static LCD COG (chip on glass) driver which can drive upto 40 segments or cascaded with two or three ML1001s to drive $80 \& 120$ segments. There is a shift register for serially shifting in the data and a data register to store the data that is going to be displayed. The display data is read into the shift register serially through the DIN pin at the rising edge of the DCLK signal. The display data will then be displayed at the rising edge of the LOAD signal. The display data in the shift register is output by the DOUT pin after 40 rising edges of the DCLK signal. The display data should be input in the sequence of SEG40, SEG39... SEG2, SEG1 for proper display of data.

## i) Power on reset

At Power on the ML1001 resets to a starting condition as follows:

1. The shift register outputs are set to GND.
2. The data register outputs are set to GND, hence all LCD segments off.

## ii) Oscillator

## a) Internal clock

The internal logic and the LCD driving signal of ML1001 are clocked either by the built-in oscillator or from an external clock. When the internal oscillator is used, OEN should be connected to GND and the OOUT should be connected to FIN. The oscillator will oscillate at 32 kHz and the frequency is independent in the range of $2.0 \mathrm{~V} \leq \mathrm{V}_{\mathrm{DD}} \leq 6.0 \mathrm{~V}$.
b) External clock

When using an external clock, the OEN is connected to VDD then connects the external clock to FIN.

## iii) Timing

ML1001 have several frequencies of clock signal for the users to choose for the LCD display clock (ie. LCLK) and the blink clock (ie. BCLK). They include the following clock signals :

| Frequency of Clock Signal at FIN $=32 \mathrm{kHz}$ | Actual Divider of FIN | Target Input Pin |
| :---: | :---: | :---: |
| 2 KHz | 1/16 | LCLK |
| 1 KHz | 1/32 |  |
| 500 Hz | 1/64 |  |
| 256 Hz | 1/128 |  |
| 128 Hz | 1/256 |  |
| 4 Hz | 1/8192 | BCLK |
| 2 Hz | 1/16384 |  |
| 1 Hz | 1/32768 |  |

## iv) Segment outputs

ML1001 has 40 segment outputs which should be connected directly to the LCD. If less than 40 segments are required, the unused segments should be left open circuit. Users can disable the first 1 to 16 segments and the last 17 to 40 segments by connecting the SEN1 and SEN2 to VDD, respectively. The segment outputs shall output GND level after disabling it.

## v) Common outputs

ML1001 consists of 2 common signals (ie. COM1A \& COM1B). These two common signals are the inversion of the LCLK. The common outputs should be left open-circuit if the outputs are unused. Users can disable the COM1A and COM1B by connecting the CEN1A and CEN1B to VDD, respectively. The common outputs will change to GND after disabling it.
vi) Blink

ML1001 has a blink function that users shall connect the BEN to GND and input the blink clock (ie. BCLK) either by connecting ML1001 output clock signal from Frequency Divider or an external clock signal. Users shall disable blink function by connecting BEN to VDD.

## * Pad Configuration



Chip Size :

| Part Number | Description | Chip Size |
| :--- | :--- | :--- |
| ML1001-1U | a 40 segment static LCD driver | 3,440 um x 600 um |
| ML1001-2U | a 80 segment static LCD driver | 6,880 um x 600 um |
| ML1001-3U | a 120 segment static LCD driver | 10,320 um x 600 um |

Chip Thickness : 400 um $\pm 25$ um
Gold Bump Pad Size : 32 um x 72 um
Gold Bump Height : 18 um $\pm 2$ um
Right Alignment mark : $(1340,-140)$
Left Alignment mark : (-1287.2, -138.2)
Origin on the center of ML1001 IC
"Positive" Mark dimension:


Note :

1. The die faces up in the diagram.

## Pad Location

All x and y coordinates are references to the center of the chip.

| PAD | PAD | Coordinate |  | $\begin{aligned} & \text { PAD } \\ & \hline \text { Num. } \end{aligned}$ | $\frac{\mathrm{PAD}}{\text { Name }}$ | Coordinate |  | $\frac{\text { PAD }}{\text { Num. }}$ | $\frac{\mathrm{PAD}}{\text { Name }}$ | Coordinate |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Num. | Name | X | Y |  |  | X | Y |  |  | X | Y |
| 1 | LOAD | -1246 | -140 | 26 | DCLK | 1054 | -140 | 51 | S21 | 20 | 140 |
| 2 | DIN | -1146 | -140 | 27 | DOUT | 1134 | -140 | 52 | S20 | -60 | 140 |
| 3 | DCLK | -1046 | -140 | 28 | LOAD | 1234 | -140 | 53 | S19 | -140 | 140 |
| 4 | BEN | -946 | -140 | 29 | GND | 1560 | -120 | 54 | S18 | -220 | 140 |
| 5 | OEN | -846 | -140 | 30 | VDD | 1560 | -40 | 55 | S17 | -300 | 140 |
| 6 | VDD | -746 | -140 | 31 | COM1B | 1560 | 40 | 56 | S16 | -380 | 140 |
| 7 | SEN1 | -666 | -140 | 32 | S40 | 1540 | 140 | 57 | S15 | -460 | 140 |
| 8 | CEN1A | -566 | -140 | 33 | S39 | 1460 | 140 | 58 | S14 | -540 | 140 |
| 9 | SEN2 | -466 | -140 | 34 | S38 | 1380 | 140 | 59 | S13 | -620 | 140 |
| 10 | CEN1B | -366 | -140 | 35 | S37 | 1300 | 140 | 60 | S12 | -700 | 140 |
| 11 | GND | -266 | -140 | 36 | S36 | 1220 | 140 | 61 | S11 | -780 | 140 |
| 12 | OOUT | -186 | -140 | 37 | S35 | 1140 | 140 | 62 | S10 | -860 | 140 |
| 13 | FIN | -86 | -140 | 38 | S34 | 1060 | 140 | 63 | S9 | -940 | 140 |
| 14 | LCLK | 14 | -140 | 39 | S33 | 980 | 140 | 64 | S8 | -1020 | 140 |
| 15 | 2 KHz | 94 | -140 | 40 | S32 | 900 | 140 | 65 | S7 | -1100 | 140 |
| 16 | 1 KHz | 174 | -140 | 41 | S31 | 820 | 140 | 66 | S6 | -1180 | 140 |
| 17 | 500 Hz | 254 | -140 | 42 | S30 | 740 | 140 | 67 | S5 | -1260 | 140 |
| 18 | 250 Hz | 334 | -140 | 43 | S29 | 660 | 140 | 68 | S4 | -1340 | 140 |
| 19 | 125 Hz | 414 | -140 | 44 | S28 | 580 | 140 | 69 | S3 | -1420 | 140 |
| 20 | 4 Hz | 494 | -140 | 45 | S27 | 500 | 140 | 70 | S2 | -1500 | 140 |
| 21 | 2 Hz | 574 | -140 | 46 | S26 | 420 | 140 | 71 | S1 | -1580 | 140 |
| 22 | 1 Hz | 654 | -140 | 47 | S25 | 340 | 140 | 72 | COM1A | -1560 | 40 |
| 23 | BCLK | 754 | -140 | 48 | S24 | 260 | 140 | 73 | VDD | -1560 | -40 |
| 24 | LCLK | 854 | -140 | 49 | S23 | 180 | 140 | 74 | GND | -1560 | -120 |
| 25 | BEN | 954 | -140 | 50 | S22 | 100 | 140 |  |  |  |  |

## * Pin Description

| Symbol | Pad | Description |
| :--- | :--- | :--- |
| LOAD | 1,28 | Load data from the shift register to data register; note 1 |
| DIN | 2 | Display data input pin |
| DCLK | 3,26 | Input pin for the clock of the display data; note 1 |
| BEN | 4,25 | Enable pin of the blink function; note 1, note 2 |
| OEN | 5 | Enable pin of the internal oscillator; note 2 |
| V $_{\text {DD }}$ | 6 | Supply voltage |
| SEN1 | 7 | Enable pin of the segment from S1 to S16; note 1 |
| CEN1A | 8 | Enable pin of the COM1A; note 2 |
| SEN2 | 9 | Enable pin of the segment from S17 to S40; note 1 |
| CEN1B | 10 | Enable pin of the COM1B; note 2 |
| GND | 11 | Logic ground |
| OOUT | 12 | Output pin of the internal oscillator |
| FIN | 13 | Input pin of the external/internal clock |
| LCLK | 14,24 | Input pin to the LCD display clock; note 1 |
| 2 kHz | 15 | Output 1/16 frequency of the input to the FIN; note 3 |
| 1 kHz | 16 | Output 1/32 frequency of the input to the FIN; note 3 |
| $512 ~ H z ~$ | 17 | Output 1/64 frequency of the input to the FIN; note 3 |
| 256 Hz | 18 | Output 1/128 frequency of the input to the FIN; note 3 |
| 128 Hz | 19 | Output 1/256 frequency of the input to the FIN; note 3 |
| 4 Hz | 20 | Output 1/8192 frequency of the input to the FIN; note 3 |
| 2 Hz | 21 | Output 1/16384 frequency of the input to the FIN; note 3 |
| 1 Hz | 22 | Output 1/32768 frequency of the input to the FIN; note 3 |
| BCLK | 23 | Input pin for the blink clock |
| DOUT | 27 | Output pin for 40-bit Shift register, it shall connect to DIN of next ML1001 |
| GND | 29 | Logic ground |
| V $_{\text {DD }}$ | 30 | Supply voltage |
| COM1B | 31 | Common driving signal to LCD panel |
| S40 to S1 | 32 to 71 | LCD segment outputs |
| COM1A | 72 | Common driving signal to LCD panel |
| V $_{\text {DD }}$ | 73 | Supply voltage |
| GND | 74 | Logic ground |
|  |  |  |

Note:

1. In cascade format of ML1001 (ie. ML1001-2U and -3U), one pin is the input of current ML1001 and the other is for the connection with the corresponding input pin of next ML1001.
2. All Enable pins are active low.
3. Condition : FIN $=32 \mathrm{KHz}$ Clock.

## * Application Examples



ML1001-1U Application Circuit with 1 Hz Blink Feature


Note : Blink at 1 Hz if $B E N=0 V$, Normal Display if $B E N=V D D$.

ML1001-1U Application Circuit with External 32 KHz Clock


Note : If External 32 KHz Clock Signal is available, designer can turn off Internal Oscillator to save power.

Note : Pin LOAD and Pin CHECK shall be connected together if the flip-chip assembly is in good condition. Hence, Pin CHECK can be served for qualifying the flip-chip assembly quality.

ML1001-2U Standard Application


| Pin | Pin Name |
| :--- | :--- |
| 1 | VDD |
| 2 | GND |
| 3 | LOAD |
| 4 | DIN |
| 5 | DCLK |
| 6 | CHECK |

Note :
Chip 1 Pad Coordinate shall follow "Table of Pad Location".
Chip 2 Pad Coordinate shall be calculated as follow :
Chip 2 X-Coordinate $=$ Chip 1 X -Coordinate +3 ,440um
Chip 2 Y-Coordinate $=$ Chip 1 Y-Coordinate

ML1001-3U Standard Application


| Pin | Pin Name |
| :--- | :--- |
| 1 | VDD |
| 2 | GND |
| 3 | LOAD |
| 4 | DIN |
| 5 | DCLK |
| 6 | CHECK |

## Note :

Chip 1 Pad Coordinate shall follow "Table of Pad Location". Chip 2 Pad Coordinate shall be calculated as follow :

Chip 2 X-Coordinate $=$ Chip 1 X-Coordinate $+3,440 \mathrm{um}$
Chip 2 Y-Coordinate $=$ Chip 1 Y-Coordinate
Chip 3 Pad Coordinate shall be calculated as follow :
Chip 3 X-Coordinate $=$ Chip 1 X-Coordinate $+6,880$ um
Chip 3 Y-Coordinate $=$ Chip 1 Y-Coordinate

## * Typical Characteristics

1) Supply Current vs. Frequency of LCLK

2) Example of Contrast Ratio vs. Input Voltage

3) Supply Current vs. Input Voltage

4) Example of Contrast Ratio vs. Viewing Angle


Note: 1. Contrast ratio of LCD shall vary from the Liquid Crystal used.
2. Contrast ratio of $1 / 3$ Duty LCD is shown on graph 4 for comparison only.
3. The viewing angle is measured from the normal of LCD as shown below.


## * Application Note

1. To ensure LCD module work properly, DCLK has to connect to $2^{\text {nd }}$ ML1001 IC for ML1001-2U configuration as shown on page 10 , or $3{ }^{\text {rd }}$ ML1001 IC for ML1001-3U configuration as shown on page 11.
2. To ensure the good flip-chip assembly quality, we suggest flip-chip bonding house add a "CHECK" pin for each COG module as shown on the section of "Application Example". Pin "LOAD" and Pin "CHECK" shall be connected together if the flip-chip assembly is in good condition. The measured resistance between Pin "LOAD" and Pin "CHECK" shall not more than 5 kohm.
3. The resistance of ITO glass shall between $15 \mathrm{ohm} / \square$ to $25 \mathrm{ohm} / \square$.
4. Each Common (ie. COM1A and COM1B) shall not cover more than $2,000 \mathrm{~mm}^{2}$ area. In case the viewing area of LCD has to be more than $2,000 \mathrm{~mm}^{2}$, OEN pin has to be connected to outside. At the time where data is transferring into the IC, internal oscillator has to be disabled through OEN pin to prevent abnormal behavior. When data transfer finishes, internal oscillator has to be enabled again.

Suggested programming steps:

| 1 | Disable internal oscillator through OEN pin |
| :--- | :--- |
| 2 | Delay (Necessary for fast MCU) |
| 3 | Transfer data through DIN, DCLK, LOAD |
| 4 | Delay (Necessary for fast MCU) |
| 5 | Enable internal oscillator through OEN pin |

Example :


Note: COM1A and COM1B shall cover half of the Viewing Area (ie. Area $=1,300 \mathrm{~mm}^{2}$ )
Each Common shall not connect to each other.

## ATTENTION



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